

ELECTRICAL PARAMETERS @ 25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ.	Max	Units
Forward Voltage (Note 1)	V_F	$I_F = 8 \text{ A}$, $T_J = 25^\circ\text{C}$ $I_F = 8 \text{ A}$, $T_J = 125^\circ\text{C}$ $I_F = 10 \text{ A}$, $T_J = 25^\circ\text{C}$		0.45 0.47	0.49 0.41 0.51	V
Reverse Break Down Voltage (Note 1)	V_{BR}	$I_R = 1 \text{ mA}$	40			V
Reverse Current (Note1)	I_R	$V_R = 35 \text{ V}$, $T_J = 25^\circ\text{C}$ $V_R = 35 \text{ V}$, $T_J = 100^\circ\text{C}$		0.1 12.5	0.3 25	mA mA
Capacitance	C_T	$V_R = 4.0\text{V}$; $f = 1 \text{ MHz}$		700		pF

Note: 1 Short duration test pulse used to minimize self – heating effect.

GRAPHS

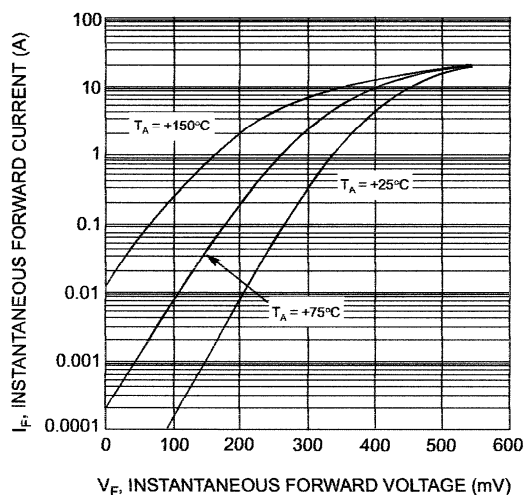


Fig. 1 Typical Forward Characteristics

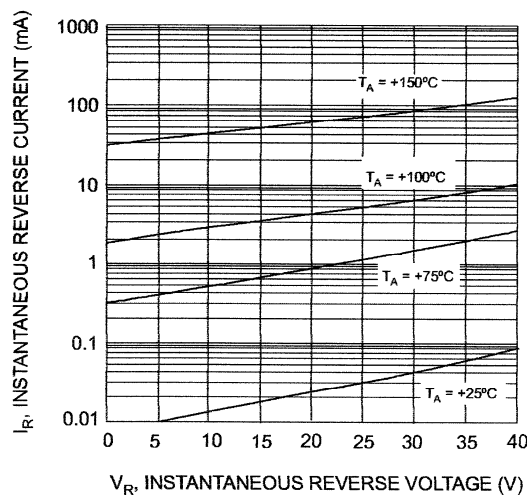


Fig. 2 Typical Reverse Characteristics

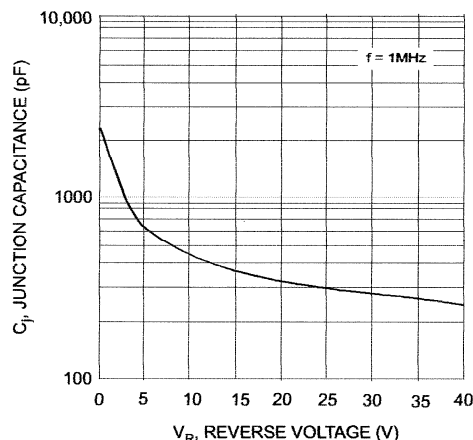
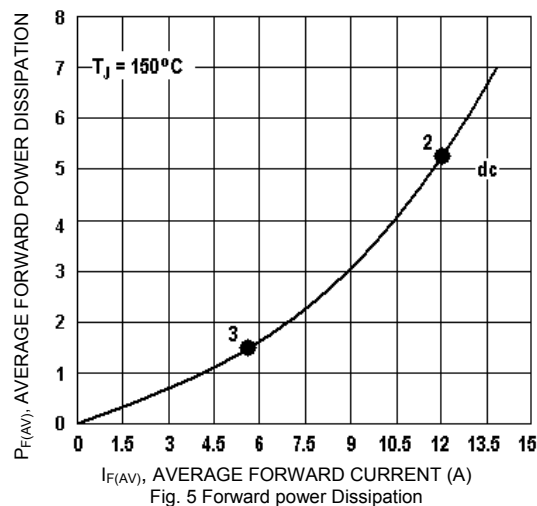
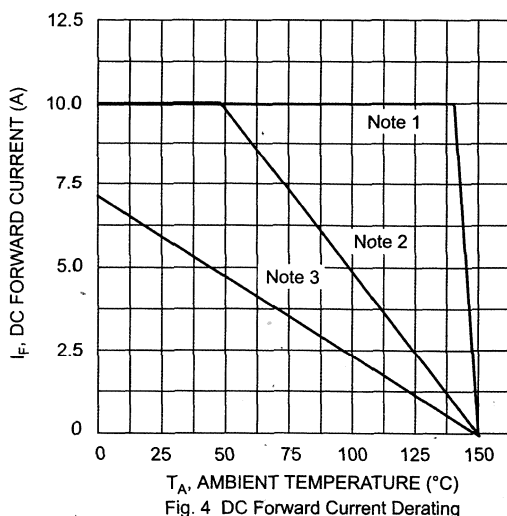


Fig. 3 Typical Junction Capacitance vs. Reverse Voltage

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NOTE 1: $T_A = T_C$ at case bottom where $R_{\theta JC} = 2.5^\circ \text{C/W}$ and $R_{\theta CA} = 0^\circ \text{C/W}$ (infinite heat sink).

NOTE 2: Device mounted on GETEK substrate, 2" x 2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". $R_{\theta JA}$ in range of 15-30° C/W.

NOTE 3: Device mounted on FRA-4 substrate, 2" x 2", 2 oz. copper, single-sided, pad layout $R_{\theta JA}$ in range of 65°C/W. See mounting pad dimensions on next page.

PACKAGE & MOUNTING PAD DIMENSIONS

PACKAGING:

	INCHES	MILLIMETERS
DIM	NOMINAL	NOMINAL
A	0.070	1.778
B	0.173	4.392
C	0.200	5.080
D	0.035	0.889
E	0.160	4.064
F	0.072	1.829
G	0.056	1.422
H	0.044	1.118
J	0.190	4.826
K	0.210	5.344
L	0.038	0.965
M	0.034	0.864
N	0.030	0.762
P	0.030	0.762

